



### NPN PRE-BIASED (R1≠R2) SMALL SIGNAL IN DFN1006

Case Material: Molded Plastic, "Green" Molding Compound.

Terminals: Finish - NiPdAu Solderable per MIL-STD-202,

UL Flammability Classification Rating 94V-0 Moisture Sensitivity: Level 1 per J-STD-020

Weight: 0.0009 grams (Approximate)

Terminal Connections: See Marking Information

### **Product Summary**

Part Number	R1 (NOM)	R2 (NOM)	Marking
DDTC123JLP	2.2kΩ	47kΩ	N0
DDTC143ZLP	4.7kΩ	47kΩ	N1
DDTC114YLP	10kΩ	47kΩ	N2

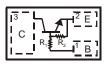
### Features

- Epitaxial Planar Die Construction
- Ultra-Small Leadless Surface Mount Package
- Ideally Suited for Automated Assembly Processes
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

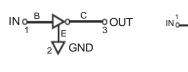
X1-DFN1006-3



Bottom View



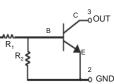
Package Pin Out Configuration



**Mechanical Data** 

Method 208 @

Case: X1-DFN1006-3



**Device Schematics** 

### Ordering Information (Note 4)

Part Number	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DDTC123JLP-7	N0	7	8	3,000
DDTC143ZLP-7	N1	7	8	3,000
DDTC114YLP-7	N2	7	8	3,000
DDTC123JLP-7B	N0	7	8	10,000
DDTC143ZLP-7B	N1	7	8	10,000
DDTC114YLP-7B	N2	7	8	10,000

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

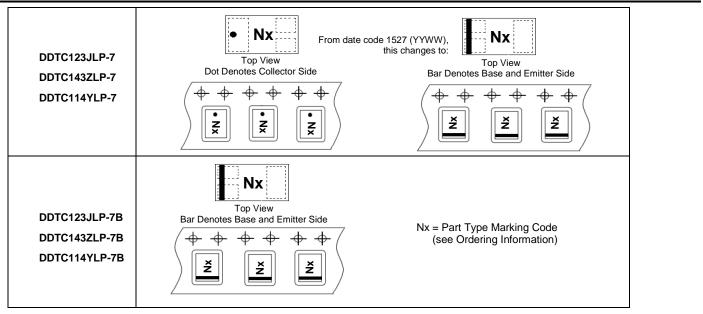
2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

For packaging details, go to our website at http://www.diodes.com/products/packages.html.

## **Marking Information**

Notes:





## Absolute Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	P/N	Symbol	Value	Unit	
Supply Voltage		Vcc	50	V	
	DDTC123JLP		-5 to +12		
Input Voltage	DDTC143ZLP	VIN	-5 to +30	V	
	DDTC114YLP		-5 to +40		
	DDTC123JLP		100		
Output Voltage	DDTC143ZLP	lo	100	mA	
	DDTC114YLP		70		
Maximum Collector Current		IC(MAX)	100	mA	

## **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	PD	250	mW
Power Deration above +25°C	P <sub>der</sub>	2	mW/°C
Thermal Resistance, Junction to Ambient Air (Note 5)	$R_{ ext{ heta}JA}$	500	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

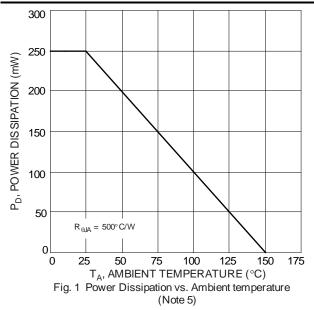
## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	P/N	Symbol	Min	Тур	Max	Unit	Test Condition
Off Characteristics (Note 6)							
Collector-Base Breakdown Voltage		BV <sub>CBO</sub>	50			V	$I_{\rm C} = 50 \mu A, I_{\rm E} = 0$
Collector-Emitter Breakdown Voltage (Note 7)		BV <sub>CEO</sub>	50			V	$I_{\rm C} = 2mA, I_{\rm B} = 0$
Emitter-Base Breakdown Voltage (Note	7)	BV <sub>EBO</sub>	4.5			V	$I_{\rm E} = 50\mu A, I_{\rm C} = 0$
Collector Cutoff Current (Note 7)		ICEX	_		0.5	μA	$V_{CE} = 50V, V_{EB(OFF)} = 3.0V$
Base Cutoff Current (I <sub>BEX</sub> )		I <sub>BL</sub>	_		0.5	μA	$V_{CE} = 50V, V_{EB(OFF)} = 3.0V$
Collector-Base Cut Off Current		I <sub>CBO</sub>	_		0.5	μA	$V_{CB} = 50V, I_E = 0$
Collector-Emitter Cut Off Current, IO(OFF	)	ICEO	_		0.5	μA	$V_{CE} = 50V, I_B = 0$
Emitter-Base Cut Off Current		I <sub>EBO</sub>			0.5	mA	$V_{EB} = 5V, I_{C} = 0$
Input-Off Voltage		VI(OFF)	0.5			V	V <sub>CE</sub> = 5V, I <sub>C</sub> = 100µA
On Characteristics (Note 6)							• · · · ·
	DDTC123JLP		_		0.85		
Base-Emitter Turn-On Voltage (Note 7)	DDTC143ZLP	V <sub>BE(ON)</sub>			0.85	V	$V_{CE} = 5V, I_C = 2mA$
	DDTC114YLP				0.95		
Base-Emitter Saturation Voltage (Note	DDTC123JLP				0.98		I <sub>C</sub> = 10mA, I <sub>B</sub> = 1mA
7)	DDTC143ZLP	(- )	_	—	0.998	V	
	DDTC114YLP			—	0.98		
Input-On Voltage		V <sub>I(ON)</sub>		—	1.1	V	$V_0 = 0.3V, I_c = 5mA$
	DDTC123JLP	lı		—	7.2	mA	
Input Current	DDTC143ZLP		_		1.5		$V_1 = 5V$
	DDTC114YLP				7.2		<u> </u>
			50			—	$V_{CE} = 5V, I_C = 1mA$
			70			—	$V_{CE} = 5V, I_C = 2mA$
DC Current Gain		h <sub>FE</sub>	125			—	$V_{CE} = 5V, I_C = 5mA$
			150		_	_	$V_{CE} = 5V, I_{C} = 10mA$
			180	—	—	—	$V_{CE} = 5V, I_{C} = 50mA$
Collector-Emitter Saturation Voltage		V <sub>CE(SAT)</sub>	—	—	0.15	V	$I_{C} = 10mA, I_{B} = 1mA$
		VCE(SAT)	_	—	0.2	V	$I_{C} = 50 \text{mA}, I_{B} = 5 \text{mA}$
Output On Voltage (Same as V <sub>CE(SAT)</sub> )		V <sub>O(ON)</sub>	_		0.3		$I_{\rm J} = 2.5 {\rm mA}, I_{\rm O} = 50 {\rm mA}$
Input Resistor +/-30%		∆R1	-30		30	%	
Resistor Ratio		∆ (R2/R1)	-20		-20	%	<u> </u>
Small Signal Characteristics		, , , , , , , , , , , , , , , , , , , ,		1		1	1
Transition Frequency (gain bandwidth product)		f⊤	—	250	—	MHz	$V_{CE} = 10V, I_E = 5mA, f = 100MHz$

5. For the device mounted on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady state condition. The entire exposed collector pad is attached to the heatsink.
6. Measured under pulsed conditions. Pulse width ≤ 300µs. Duty cycle ≤ 2%.
7. Guaranteed by design. Notes:

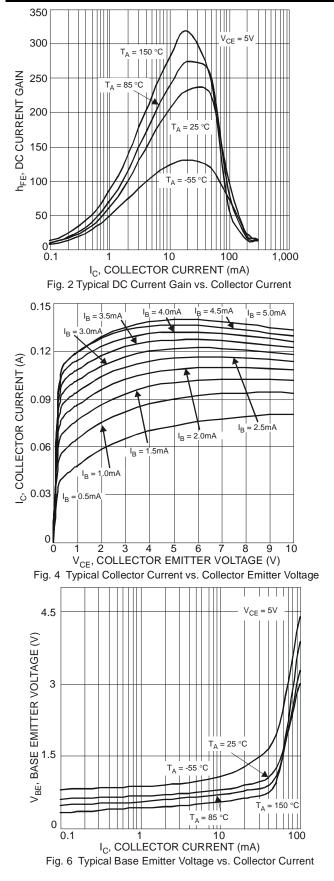


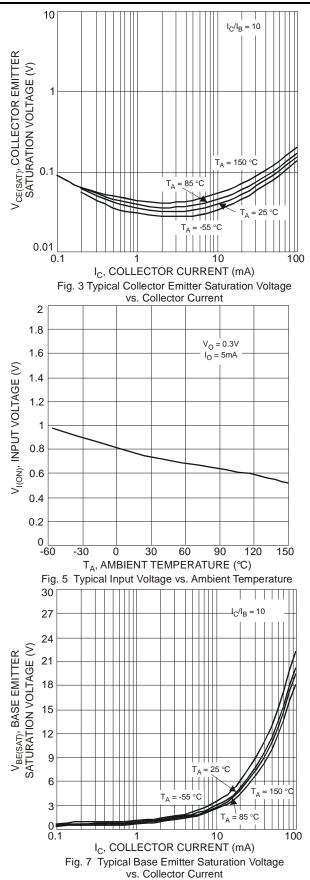
## Derating Curve (@T<sub>A</sub> = +25°C, unless otherwise specified.)





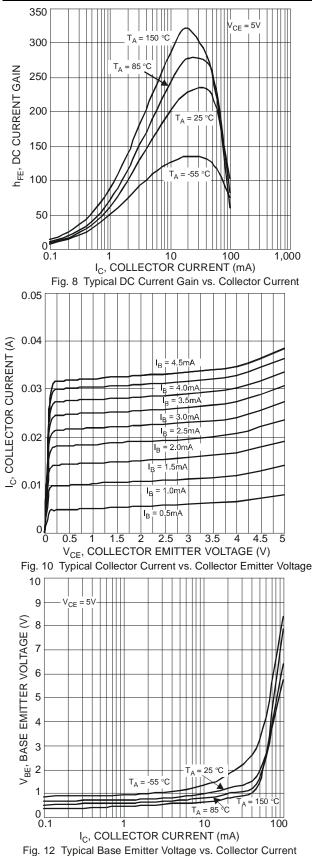
# Typical Electrical Characteristics of DDTC123JLP (@T<sub>A</sub> = +25°C, unless otherwise specified.)

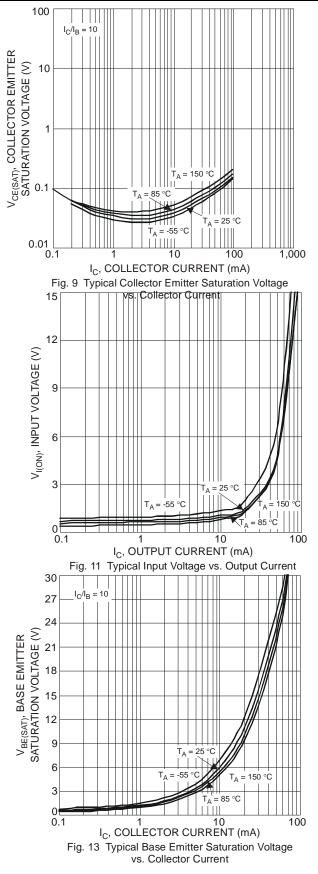






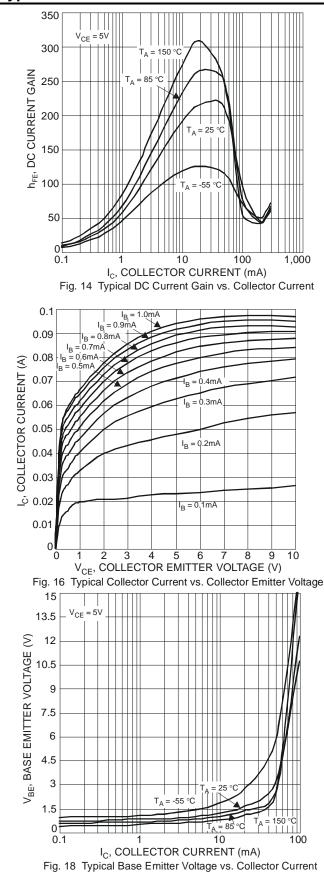
# **Typical Electrical Characteristics of DDTC143ZLP** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

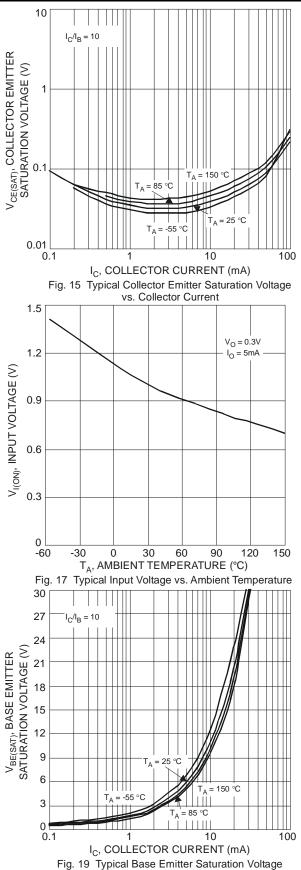






# Typical Electrical Characteristics of DDTC114YLP (@T<sub>A</sub> = +25°C, unless otherwise specified.)



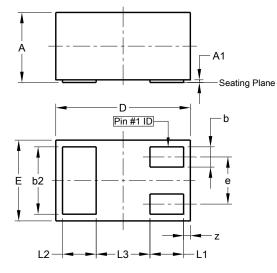


vs. Collector Current



# **Package Outline Dimensions**

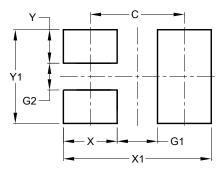
Please see AP02001 at http://www.diodes.com/\_files/datasheets/ap02001.pdf for the latest version.



X1-DFN1006-3					
Dim	Min	Max	Тур		
Α	0.47	0.53	0.50		
A1	0.00	0.05	0.03		
b	0.10	0.20	0.15		
b2	0.45	0.55	0.50		
D	0.95	1.075	1.00		
Е	0.55	0.675	0.60		
е	-	-	0.35		
L1	0.20	0.30	0.25		
L2	0.20	0.30	0.25		
L3	-	-	0.40		
z	0.02	0.08	0.05		
All D	All Dimensions in mm				

## Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/\_files/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.70
G1	0.30
G2	0.20
Х	0.40
X1	1.10
Y	0.25
Y1	0.70



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